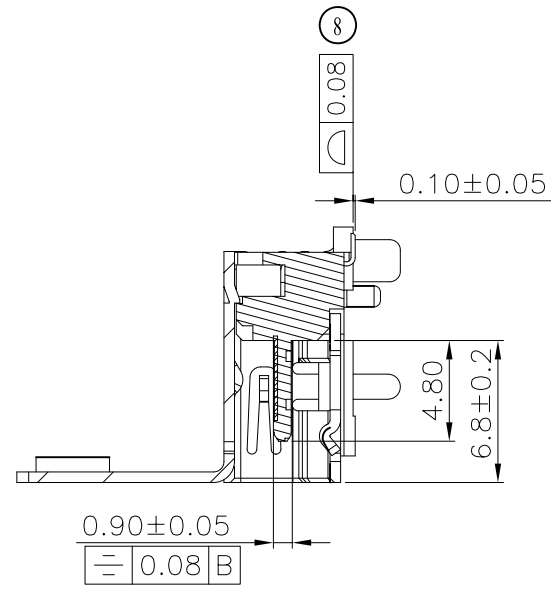
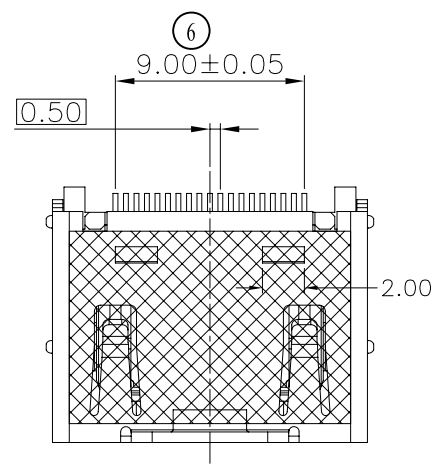
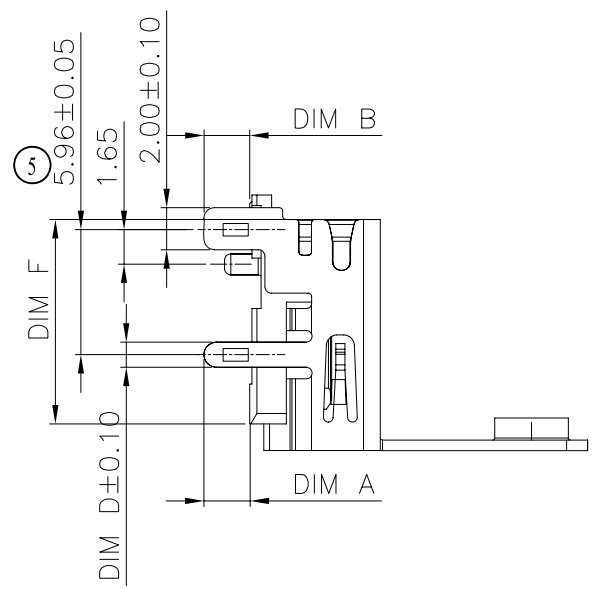
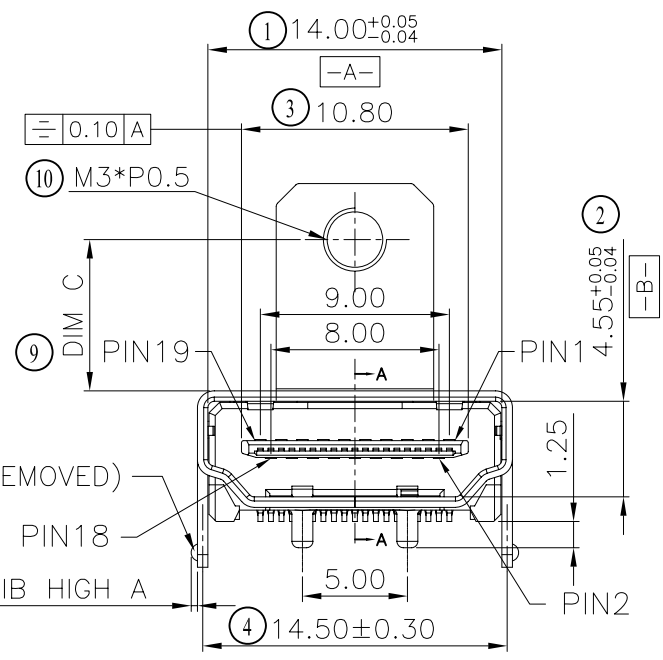


A	新版发行	CHU	2010-03-19
Rev. 版本	CHANGE DESCRIPTION 变更内容	REVISOR 制/修订人	DATE 日期

MATERIAL	TOLERANCE UNSPECIFIED			ZheJiang HeFeng Technology Co.,Ltd		
	0.0 ±0.38	0°. ±2'		SCALE	UNIT	
FINISH	0.00 ±0.25	.0° ±1'	1:1	mm	SHEET	
	0.000 ±	.0° ±0.5'	NAME			
	DRAWN chu 10/03/19		HDMI A/F 19PIN SMT TYPE			1/3
	DESIGNER		DRAWING NO.			REV
CHECKED		HHF-2XXXXX-XSA		A		
APPROVED						



SECTION A-A
SCALE 1:1



RIB
(CAN BE REMOVED)

PIN 18

⑦ 4-RIB HIGH A

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MATERIAL	TOLERANCE UNSPECIFIED		ZheJiang HeFeng Technology Co.,Ltd	
	0.0 ±0.38	0° ±2'	SCALE	UNIT
FINISH	0.00 ±0.25	.0° ±1'	1:1	mm
	0.000 ±	.0° ±0.5'	NAME	SHEET
			HDMI A/F 19PIN SMT TYPE	2/3
			DRAWING NO. HHF-2XXXXX-XSA	REV A

NOTES:

1. MATERIAL:
 - 1.1 HOUSING: HIGH TEMPERATURE THERMOPLASTIC UL 94V-0 RATED
 - 1.2 SHELL: C2680 R-H (S50C T=0.5mm)
 - 1.3 TERMINAL: C2680 R-H
 - 1.4 MYLAR:
2. PLATING:
 - 1.1 SHELL: GOLD PLATING OVER NICKEL
UNDERPLATED/NICKEL PLATING OVER ALL
 - 1.2 TERMINAL: GOLD PLATING ON CONTACT AREA AND
TIN PLATING ON SOLDER AREA,
NICKEL UNDERPLATING OVER ALL
3. ALL RAW MATERIAL, COMPONENTS, AND PROCESS MUST
MEET HAZARD SUSTAIN FREE PER RoHS & REACH STANDARD.

4. P/N: HHF-2 X X X X X- X S A

SHELL MATERIAL & PLATING CODE:

- 1: MATERIAL: COPPER ALLOY
NICKEL PLATING WITH FLANGE
- 2: MATERIAL: COPPER ALLOY
NICKEL PLATING WITHOUT FLANGE
- 3: MATERIAL: S50C T=0.5mm
NICKEL PLATING WITH FLANGE
- 4: MATERIAL: S50C T=0.5mm
NICKEL PLATING WITHOUT FLANGE
- 5: MATERIAL: COPPER ALLOY
GOLD PLATING WITH FLANGE
- 6: MATERIAL: COPPER ALLOY
GOLD PLATING WITHOUT FLANG

REV. CODE

PACKING CODE

- 1: TARY PACKING
- 2: TAPE REEL PACKAGEING
- 3: TUBE PACKING

FLANGE & RIB HIGH:

CODE	DIM F	RIB HIGH
0	9.75	0.00
1	9.75	0.15
2	9.75	0.30
3	7.20	0.00
4	7.20	0.15
5	7.20	0.30

TERMINAL PLATING CODE:

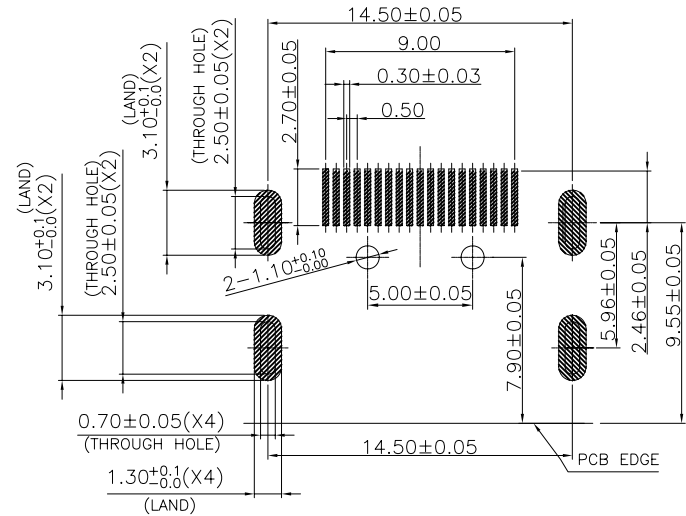
- 1: CONTACT AREA: GOLD FLASH
SOLDER AREA: GOLD FLASH
- 2: CONTACT AREA: 3u" GOLD
SOLDER AREA: GOLD FLASH
- 3: CONTACT AREA: 15u" GOLD
SOLDER AREA: GOLD FLASH
- 4: CONTACT AREA: 30u" GOLD
SOLDER AREA: GOLD FLASH
- A: CONTACT AREA: GOLD FLASH
SOLDER AREA: MATTE TIN 100u"
- B: CONTACT AREA: 3u" GOLD
SOLDER AREA: MATTE TIN 100u"
- C: CONTACT AREA: 15u" GOLD
SOLDER AREA: MATTE TIN 100u"
- D: CONTACT AREA: 30u" GOLD
SOLDER AREA: MATTE TIN 100u"

SHELL LEG&FLANGE HIGH CODE:

CODE	DIM A	DIM B	DIM D
0	1.80	2.20	1.00
1	2.20	2.20	1.20
2	2.20	2.20	1.20
3	2.20	2.20	1.00
4	2.20	2.20	1.00
5	2.20	2.20	1.00

COVER & MYLAR:

CODE	MYLAR	COVER
0	W/O	W/O
1	W	W/O
3	W/O	W
4	W	W



**RECOMMENDED PCB LAYOUT
(THICKNESS=1.6±0.15mm)**

RIB HIGH A		0.15	0.30
DIM.E		0.90	1.10

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	0.0 ±0.38	0.° ±2'	SCALE 1:1	UNIT mm
	0.00 ±0.25	.0' ±1'		
	0.000 ±	.0' ±0.5'		
FINISH	DRAWN		NAME	
	DESIGNER		HDMI A/F 19PIN SMT TYPE	
	CHECKED		DRAWING NO.	
	APPROVED		HHF-2XXXXX-XSA	
			SHEET	3/3
			REV	A